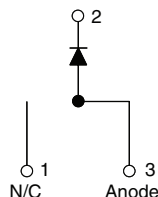


HEXFRED®

Ultrafast Soft Recovery Diode, 4 A


D-PAK


FEATURES

- Ultrafast recovery time
- Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- Guaranteed avalanche
- Specified at operating temperature
- Lead (Pb)-free
- Designed and qualified for Q101 level



RoHS*
COMPLIANT

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION/APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for freewheeling, flyback, power converters, motor drives, and other applications where high speed and reduced switching losses are design requirements.

PRODUCT SUMMARY

V_R	600 V
V_F at 4 A at 25 °C	1.8 V
$I_{F(AV)}$	4 A
t_{rr} (typical)	17 ns
T_J (maximum)	150 °C

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_{RRM}		600	V
Maximum continuous forward current	$I_{F(AV)}$	$T_C = 100\text{ °C}$	4	A
Single pulse forward current	I_{FSM}		25	
Repetitive peak forward current	I_{FRM}	$T_C = 116\text{ °C}$	16	
Maximum power dissipation	P_D	$T_C = 100\text{ °C}$	10	W
Operating junction and storage temperatures	T_J, T_{Stg}		- 55 to 150	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage See fig. 1	V_F	$I_F = 4\text{ A}$	-	1.5	1.8	
		$I_F = 8\text{ A}$	-	1.8	2.2	
		$I_F = 4\text{ A}, T_J = 125\text{ °C}$	-	1.4	1.7	
Maximum reverse leakage current	I_R	$V_R = V_R$ rated	-	0.17	3.0	μA
		$T_J = 125\text{ °C}, V_R = 0.8 \times V_R$ rated	-	44	300	
Junction capacitance	C_T	$V_R = 200\text{ V}$	-	4	8	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

* Pb containing terminations are not RoHS compliant, exemptions may apply

DYNAMIC RECOVERY CHARACTERISTICS ($T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1.0\text{ A}$, $di_F/dt = 200\text{ A}/\mu\text{A}$, $V_R = 30\text{ V}$	-	17	-	ns
		$T_J = 25\text{ }^{\circ}\text{C}$	-	28	42	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	38	57	
Peak recovery current	I_{RRM}	$T_J = 25\text{ }^{\circ}\text{C}$	-	2.9	5.2	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	3.7	6.7	
Reverse recovery charge	Q_{rr}	$T_J = 25\text{ }^{\circ}\text{C}$	-	40	60	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	70	105	
Rate of fall of recovery current	$di_{(rec)M}/dt$	$T_J = 25\text{ }^{\circ}\text{C}$	-	280	-	A/ μs
		$T_J = 125\text{ }^{\circ}\text{C}$	-	235	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		- 55	-	150	$^{\circ}\text{C}$
Soldering temperature	T_S	10 s	-	-	240	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction to case	R_{thJC}		-	-	5.0	
Thermal resistance, junction to ambient	R_{thJA}	Typical socket mount	-	-	80	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style D-PAK	HFA04SD60S			

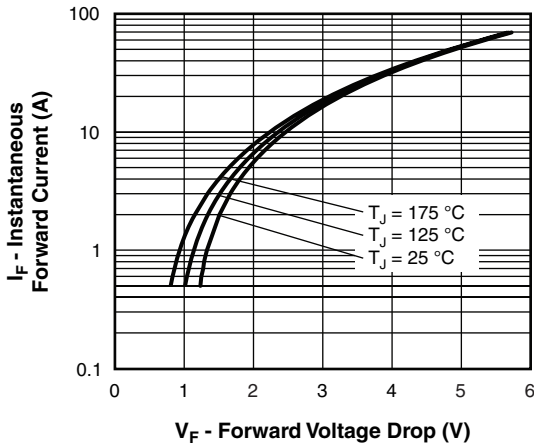


Fig. 1 - Typical Forward Voltage Drop Characteristics

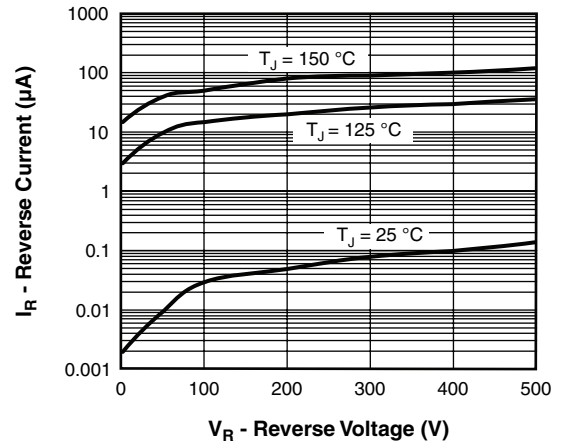


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

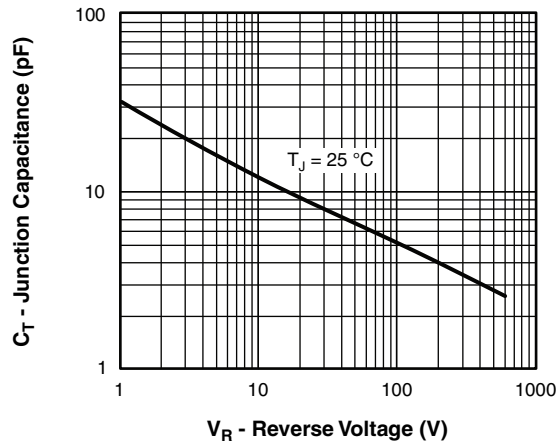


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

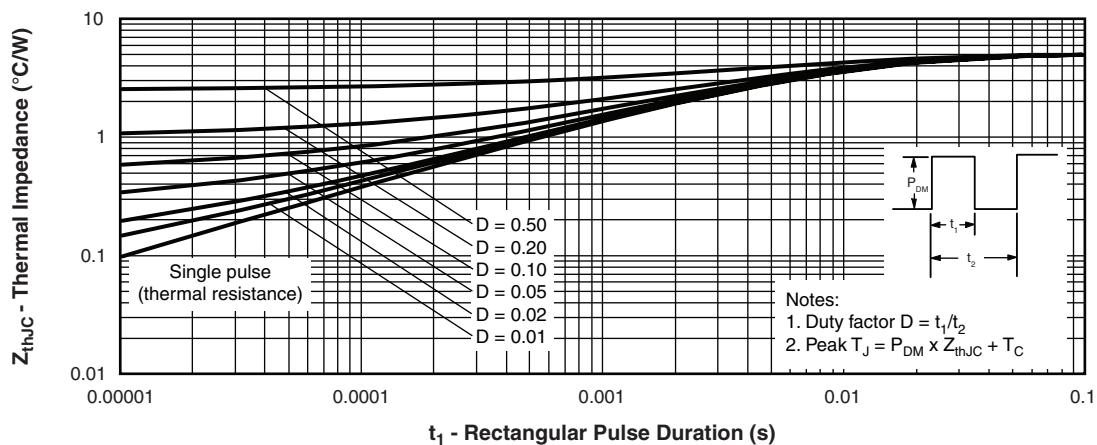
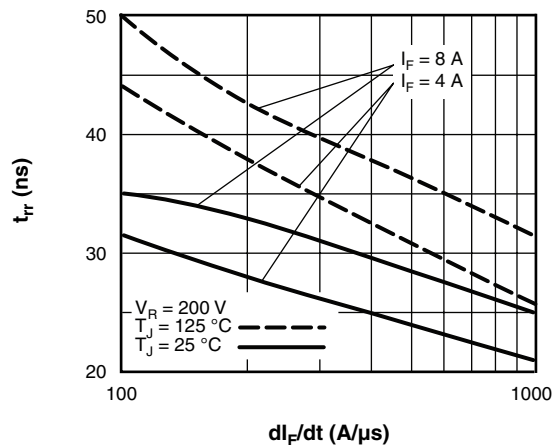
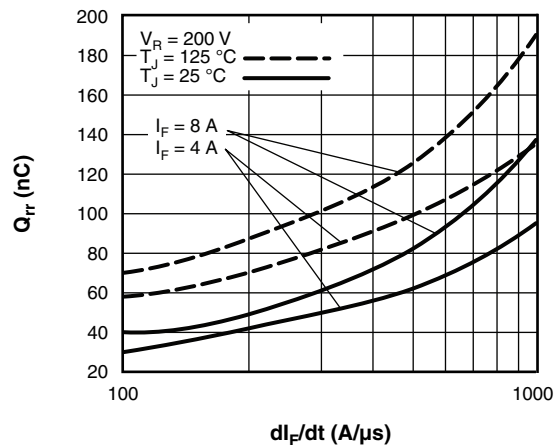
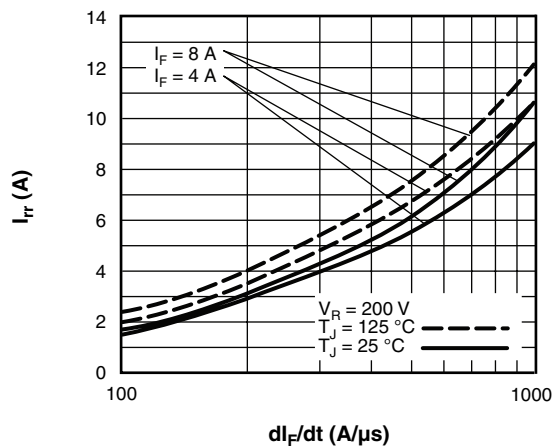
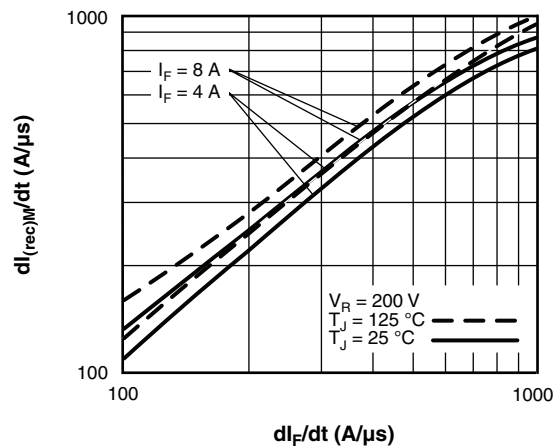


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt Fig. 7 - Typical Stored Charge vs. dI_F/dt Fig. 6 - Typical Recovery Current vs. dI_F/dt Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt

HEXFRED® Ultrafast Soft Recovery Diode, 4 A

Vishay High Power Products

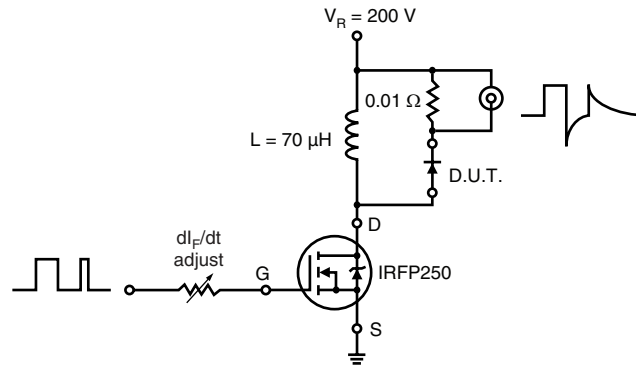


Fig. 9 - Reverse Recovery Parameter Test Circuit

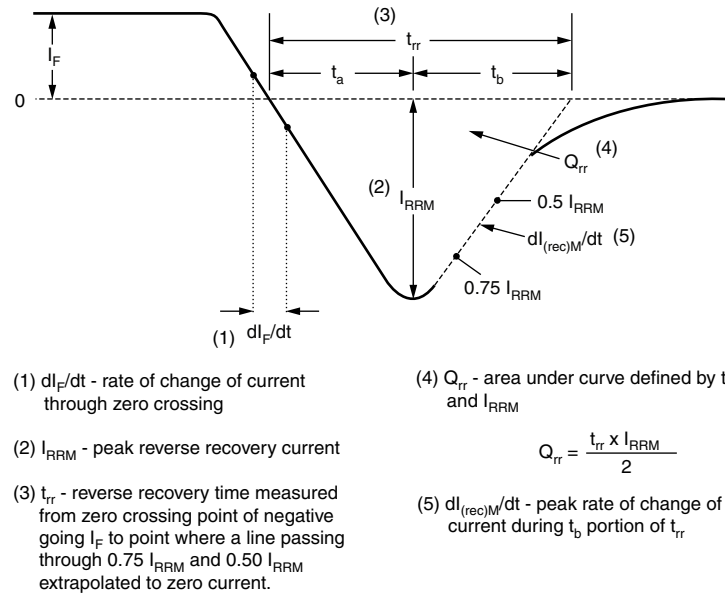


Fig. 10 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code	HFA	A	04	SD	60	S	PbF
	1	2	3	4	5	6	7
1	- HEXFRED® family						
2	- Electron irradiated						
3	- Current rating (04 = 4 A)						
4	- D-PAK						
5	- Voltage rating (60 = 600 V)						
6	- Suffix						
7	- • None = Standard production						
	• PbF = Lead (Pb)-free						

S = D²PAK/D-PAK
 TR = Tape and reel
 TRL = Tape and reel left
 TRR = Tape and reel right

LINKS TO RELATED DOCUMENTS	
Dimensions	http://www.vishay.com/doc?95016
Part marking information	http://www.vishay.com/doc?95059
Packaging information	http://www.vishay.com/doc?95033



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